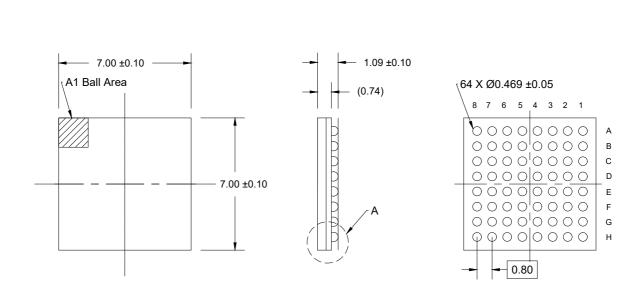


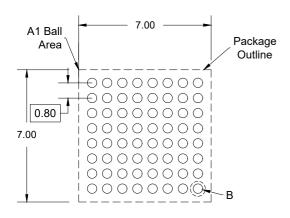


Package Code: BJG64

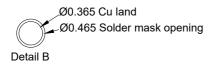
64-BGA 7.00 x 7.00 x 1.09 mm Body, 0.80 mm Pitch PSC-4979-01, Revision: 01, Date Created: Mar 14, 2023



TOP VIEW

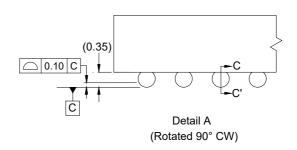


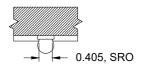
RECOMMENDED LAND PATTERN (PCB Top View, NSMD Design)



SIDE VIEW

BOTTOM VIEW





Detail C - C'

NOTES:

- 1. JEDEC compatible.
- 2. All dimensions are in mm and angles are in degrees.
- 3. Use ±0.05 mm for the non-toleranced dimensions.
- 4. Numbers in () are for references only.
- 5. Pre-reflow solderball diameter is Ø0.45 mm.